LM3495 Buck Controller Evaluation Module User's Guide



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Specifications Of The Board Www.ti.com

1 Specifications Of The Board

The evaluation board has been designed to test various circuits using the LM3495 buck regulator controller. Figure 10-1 shows a complete schematic for all components. The board has four layers, consisting of signal/power traces on the top and bottom, one internal ground plane, and an internal split power plane. The top and bottom planes are 1-oz. copper, internal planes are 1/2 oz., and the board is 62-mil FR4 laminate.

2 Example Circuit

The example circuit that comes on the evaluation board steps input voltages of 12 V ±10% down to 1.2 V at currents up to 10 A with a switching frequency of 500 kHz. The measured efficiency of the converter is 86% at an output current of 7 A.

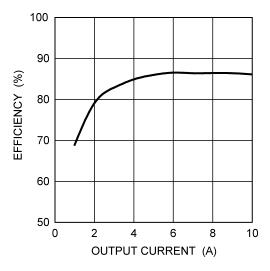


Figure 2-1. Efficiency for $V_{IN} = 12 \text{ V}$

3 Powering The Converter

The example circuit for the LM3495 evaluation board is optimized to run at inputs of 12 V, however the circuit will operate with input voltages ranging from 2.9 V to 18.0 V connected between the 'VIN' and 'GND' terminals at the top of the board. Fixed loads, resistors, and variable electronic loads can be connected between the 'Vo' and 'GND' terminals. Table 13-1 lists all the components used in the example circuit.

4 Enabling The Converter

The SPDT switch *ON/OFF* controls the state of the converter while power is applied to the input terminals. While in the OFF position the COMP/SD* pin of the LM3495 is grounded, the output is disabled, and the IC enters a low power state. While in the ON position the output voltage is regulated and is capable of delivering current to a load connected at the output terminals.

www.ti.com Testing The Converter

5 Testing The Converter

Figure 11-1 shows a block diagram of connections for making measurements of efficiency. The wires used for making connections at both the input and output should be rated to at least 10 A of continuous current and should be no longer than is needed for convenient testing. A series ammeter capable of measuring 10 A or more should be used for both the input and the output lines. Dedicated voltmeters should be connected with their positive and negative leads right at the four power terminals at the top of the evaluation board. This measurement technique minimizes the voltage loss in the wires that connect the evaluation board to the input power supply and the electronic load.

Output voltage ripple measurements should be taken directly across the 100-nF ceramic capacitor, *Cox*, placed right between the output terminals. Care must be taken to minimize the loop area between the oscilloscope probe tip and the ground lead. One method to minimize this loop is to remove the spring tip and 'pigtail' ground lead of the probe and then wind bare wire around the probe shaft. The bare wire should contact the ground of the probe and the end of the wire can then contact the ground side of *Cox*. Figure 11-2 shows a diagram of this method.

An oscilloscope probe modified as described above can also be used to measure the switch node voltage, LG pin voltage, and HG pin voltage (all three with respect to ground) using the 40-mil diameter hole pairs labeled "+ SW -", "+ LG -", and "+ HG -", respectively.

6 SKIP/PWM

A second SPDT switch labeled SKIP/FPWM determines that control scheme the LM3495 uses at low output currents. When set to SKIP, the converter saves energy during light loads (approximately 100 mA or less) by using the body diode of the low-side FET, as well as leaving the high-side FET off if possible. When the switch is set to FPWM, the LM3495 forces both top and bottom FETs to switch during every cycle, regardless of the load current.

7 MOSFET Footprints

The LM3495 evaluation board has footprints for single N-MOSFETs with SO-8 packages and standard pinouts. These footprints can also accept newer MOSFET packages that are compatible with SO-8 footprints. See Figure 7-1. *Q1* is the high-side FET and *Q2* low-side FET.

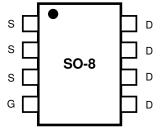


Figure 7-1. SO-8 MOSFET Pinout

8 Permanent Components

The following components should remain the same for any new circuits evaluated on the LM3495 evaluation board:

Name	Value
Cb	0.1 μF
Cf	1 μF
Cdd	2.2 µF

9 Additional Footprints

A 100-pF ceramic capacitor should be placed at position *Dsync* whenever the LM3495 runs without an external clock. When an external clock is used, *Dsync* should be removed and a 100-pF ceramic capacitor placed at *Csync*.

The $0-\Omega$ resistor *J1* connects the TRACK pin and VDD pins of the LM3495 together. It should be removed only when the tracking function is used.

The $0-\Omega$ resistor J2 connects the VIN and VLIN5 terminals of the LM3495 together. This resistor should be used only when the input voltage is 5.5 V or less to provide maximum MOSFET gate drive.

The $0-\Omega$ resistor *J3* connects the 'VIN' terminal to the VIN pin of the LM3495. This resistor should be removed only for testing of the input current draw of the LM3495 IC.

The $0-\Omega$ resistor *Rbst* can be replaced with a higher value resistor to limit the current drawn by the BOOST pin. This slows the high-side FET gate drive rise time and can reduce ringing on the switch node. Care must be taken, as slowing the gate drive too much can cause shoot-through current.

Components Rt1 and Rt2 are used if the output of the converter is tracking another supply during start-up. For this application, the output of the external supply should be connected to the TRACK IN terminal. When the tracking feature is not used, the track pin should be connected to the VDD pin by placing a $0-\Omega$ resistor in position J2.

Components Rsnb and Csnb can be used to filter ringing on the switch node.

D2 provides a position for a diode to go in parallel with Q2. In circuits with output currents of approximately 5 A or less, a Schottky diode at D2 can improve the efficiency of the converter.



10 Complete Circuit Schematic

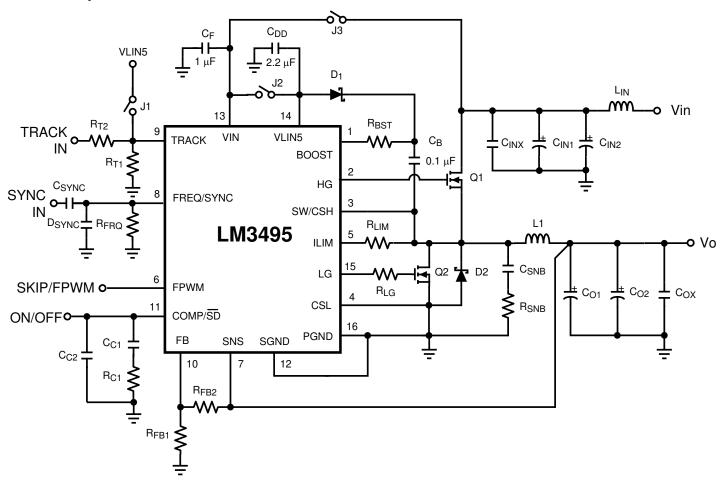


Figure 10-1. Circuit Schematic

Connection Diagrams www.ti.com

11 Connection Diagrams

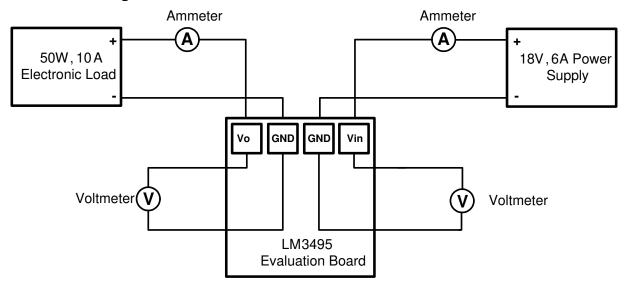


Figure 11-1. Efficiency Measurement Setup

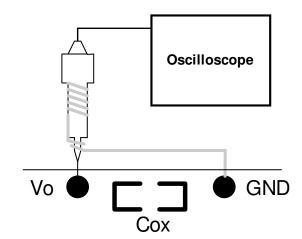


Figure 11-2. Output Voltage Ripple Measurement Setup



12 Typical Performance Waveforms

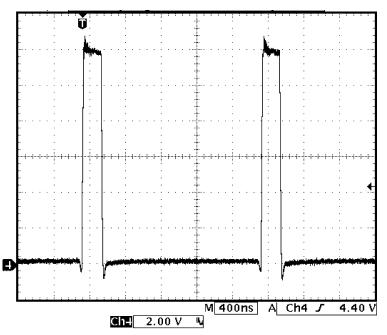


Figure 12-1. Switch Node Voltage (V_{IN} = 12 V, V_{O} = 1.2 V, I_{O} = 5 A)

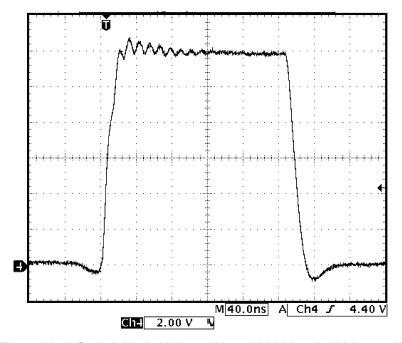


Figure 12-2. Switch Node Voltage (V_{IN} = 12 V, V_{O} = 1.2 V, I_{O} = 5 A)

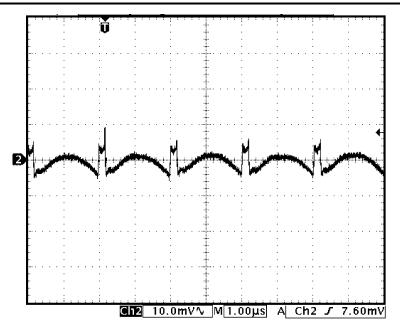


Figure 12-3. Output Voltage Ripple, AC Coupled (V_{IN} = 12 V, V_{O} = 1.2 V, I_{O} = 5 A)

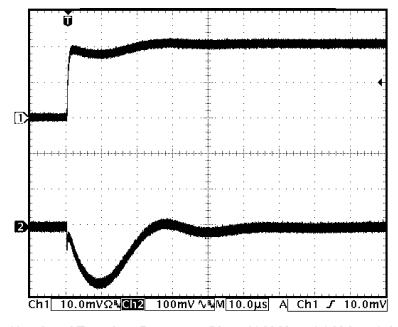


Figure 12-4. Load Transient Response (V_{IN} = 12 V, V_{O} = 1.2 V, I_{O} = 0 A to 4 A)



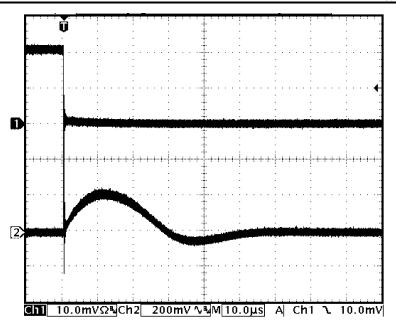


Figure 12-5. Load Transient Response (V_{IN} = 12 V, V_{O} = 1.2 V, I_{O} = 4 A to 0 A)

Bill of Materials (BOM) www.ti.com

13 Bill of Materials (BOM)

Table 13-1. Bill of Materials (BOM)

Table 13-1. Bill of Materials (BOM) Qtv ID Part Number Type Size Parameters Vendor									
Qty		Part Number	Туре	Size	Parameters	Vendor			
1	U1	LM3495	Synchronous Controller	TSSOP-16		TI			
1	Q1	HAT2198R	N-MOSFET	SO-8	30 V, 9.6 mΩ 11 nC	Renesas			
1	Q2	HAT2165H	N-MOSFET	LFPAK	30 V 3.4 mΩ, 33 nC	Renesas			
1	D1	MBR0530	Schottky Diode	SMA	30 V, 0.5 A	Vishay			
1	L1	RLF12560T-1R0N140	Inductor	12.5x12.8 x6.0mm	1 μH, 14 A, 3 mΩ	TDK			
1	Cin	C3225X5R1E226M	Capacitor	1210	22 μF, 25 V	TDK			
2	Co1, Co2	C3225X5R0J107M	Capacitor	1210	100 μF, 6.3 V, 1 mΩ	TDK			
1	Cf	C3216X7R1E105M	Capacitor	1206	1 μF, 25 V	TDK			
1	Cdd	C3216X7R1E225M	Capacitor	1206	2.2 μF, 25 V	TDK			
2	Cb, Cinx	VJ1206Y104KXXAT	Capacitor	1206	100 nF, 10%	Vishay			
1	Cc1	VJ1206Y103KXXAT	Capacitor	1206	10 nF, 10%	Vishay			
3	Cc2, Csync, Dsync	VJ1206A101KXXAT	Capacitor	1206	100 pF, 10%	Vishay			
1	Cox	VJ0805Y104KXXAT	Capacitor	805	100 nF, 10%	Vishay			
3	Rbst, J1, J3	CRCW08050R00F	Resistor	805	0 Ω	Vishay			
1	Lin	CRCW25120R00F	Resistor	2512	0 Ω	Vishay			
1	Rc1	CRCW12061501F	Resistor	1206	1.5 kΩ, 1%	Vishay			
2	Rfb1, Rfb2	CRCW12061002F	Resistor	1206	10 kΩ, 1%	Vishay			
1	Rfrq	CRCW12065492F	Resistor	1206	54.9 kΩ, 1%	Vishay			
1	Rlg	CRCW12061R00F	Resistor	1206	1 Ω, 1%	Vishay			
1	Rlim	CRCW12063321F	Resistor	1206	3.32 kΩ, 1%	Vishay			
2	SKIP/FPWM ON/OFF	NKK A12AB	SPST			NKK			
5	Vo, GND1 GND2, GND3 Vin	Newark 40F6004	Terminal Silver	0.094"		Cambion			
4	SYNC IN GND4, GND5 TRACK IN	Newark 94F1478	Terminal Silver	0.062"		Keystone			

14 PCB Layout



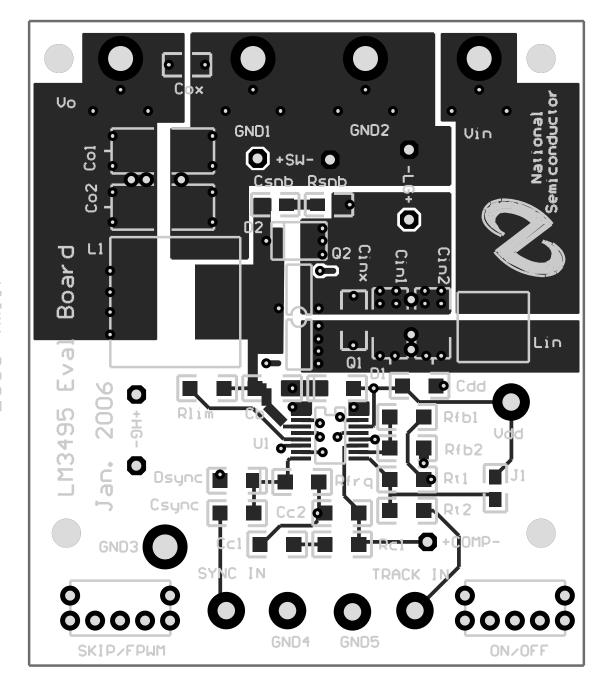


Figure 14-1. Top Layer and Top Overlay

PCB Layout Www.ti.com

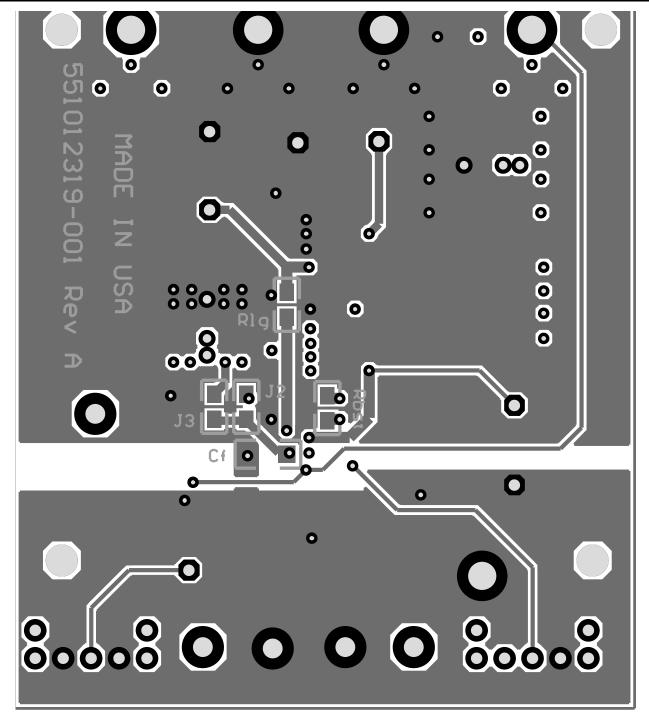


Figure 14-2. Bottom Layer

www.ti.com PCB Layout

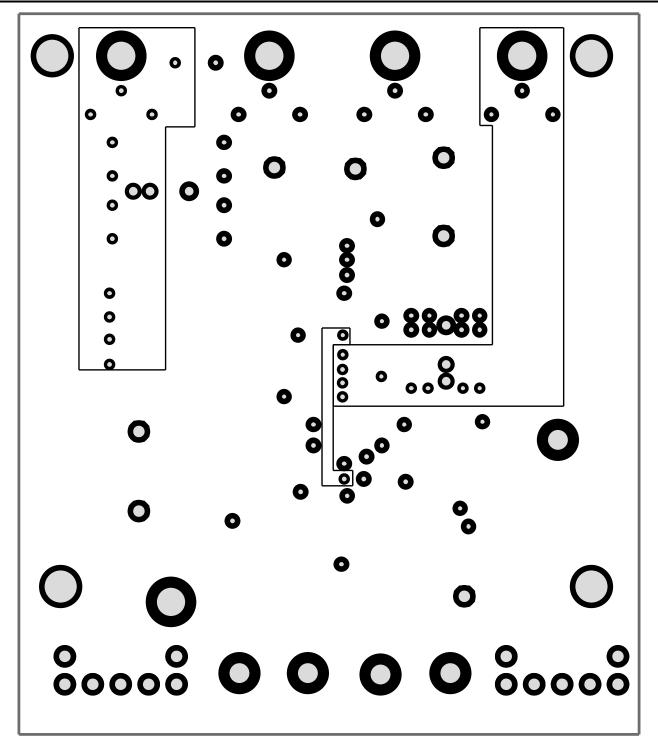


Figure 14-3. Internal Layer 1

Revision History Www.ti.com

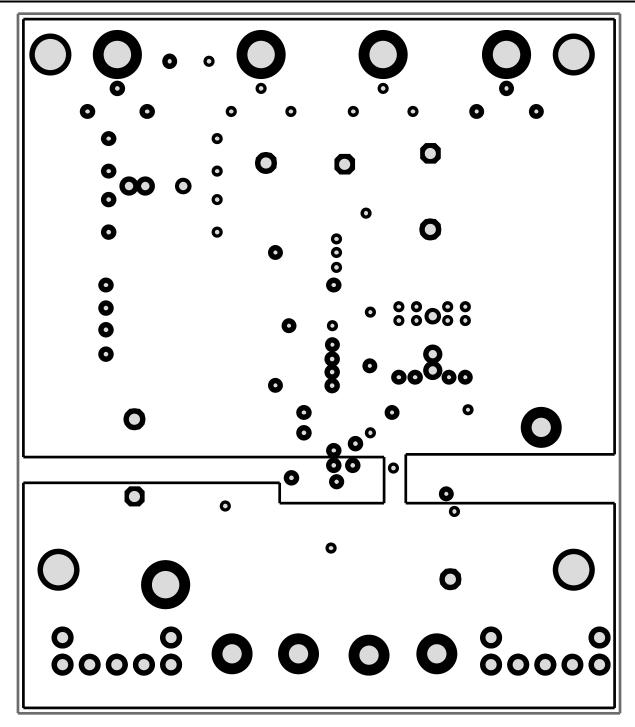


Figure 14-4. Internal Layer 2

15 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision B (April 2013) to Revision C (February 2022)	Page
•	Updated the numbering format for tables, figures, and cross-references throughout the document	2
•	Updated the user's guide title	
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